Feedpool Technology Co., Ltd.

Technical Data Sheet

EP-2009-6-H-90

B-Stageable Adhesive

Introduction:

EP-2009-6-H-90 is designed for use in laminate-based application. This material is ideal for sealing of glass / metal with various substrates in IC / LED/ Electronic application where bleed needs to be minimized.

Features

- Dispense by write
- Low moisture uptake
- Low warpage

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Density	1.15 g/cc	Pycnometer	FT-P001
Appearance	black		
Viscosity @ 25℃	18000– 24000 cps	Brookfield DV-Ⅲ/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25℃	1.7-2.2	Brookfield DV-Ⅲ/CP-51 Visc @ 0.5rpm/Visc @ 5rpm	FT-P008
Grind	＜20μm	Grindmeter	FT-P025
Work Life @ 25℃	48 hours	25% increase in visc. @ 5rpm	FT-P024
Shelf Life @ -40℃	6 months		FT-P018
CURE CONDITION		**TEST DESCRIPTION**	**TEST METHOD**
B-stage Cure Condition		45 - 60 min @ 100 ℃	
C-stage Cure Condition		60 – 90 min @150 - 170 ℃ (The higher temperature and the longer cure time, the higher Tg results)	
MECHANICAL PROPERTIES-POST CURE		**TEST DESCRIPTION**	**TEST METHOD**
Die Shear Strength @ 25℃	12 Kg/die	2x2mm Si die on Microscope Slide Glass	FT-M012
Die Shear Strength @260℃	4 Kg/die	2x2mm Si die on Microscope Slide Glass	FT-M012

The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

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PHYSIOCHEMICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature	89 ℃	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		TMA Expansion Mode	FT-M016
Below Tg	47 ppm/℃		
Above Tg	140 ppm/℃		
Dynamic Tensile Modulus		Dynamic Mechanical Thermal Analysis using <1.5 mm thick Specimen	FT-M019
@ -60℃	4200 MPa		
@25℃	2800 MPa		
@150℃	95 MPa		
@250℃	81 MPa		

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